

Appl. No. 10/825,718  
Reply dated August 26, 2006  
Reply to Final Office Action mailed March 21, 2006

1. Amendments to the Claims:

1 - 8. Cancelled.

9. (Previously Amended) A method for fabricating a cleaning device whose working surface is capable of being detected by a probe device, the method comprising:

forming a cleaning device having a working surface by forming a first release liner layer, forming a cleaning pad layer having a working surface on the first release liner layer, forming an adhesive layer on the cleaning pad layer, and forming a second release liner layer on the adhesive layer wherein the first release liner layer is removed to create the matte finish of the working surface; and

removing a layer from the working surface wherein the removal of the layer imparts a matte finish to the working surface of the cleaning device.

10 - 15. Cancelled.

16. (Previously Amended) A method for testing semiconductor devices in an automatic cleaning mode, the method comprising:

performing testing of semiconductor devices;

during the testing operation, automatically determining that a cleaning is to be performed;

automatically determining the location of a working surface of a cleaning device based on a characteristic of the working surface by directing optical energy towards the working surface of the cleaning device and determining the location of the working surface of the cleaning device based on the optical energy reflected off of the working surface of the cleaning device;

performing the cleaning using the cleaning device; and

continuing the testing of semiconductor devices.

17. (Previously Amended) The method of Claim 16, wherein determining the working surface of the cleaning device further comprises measuring the conductance of the working

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surface of the cleaning device in order to determine the position of the working surface of the cleaning device.

18. (Previously Amended) The method of Claim 16, wherein performing the cleaning further comprises moving a probe element in a horizontal motion.

19. (Previously Amended) The method of Claim 16, wherein performing the cleaning further comprises moving a probe element in an orbital motion.

20 - 22. Cancelled.

23. (Previously Amended) The method of Claim 25, wherein determining that cleaning is to be performed further comprises measuring the parameters of each semiconductor device being tested and initiating a cleaning step when the measured parameters vary from a normal value.

24. (Previously Amended) The method of Claim 25, wherein determining that cleaning is to be performed further comprises performing a cleaning step after a predetermined number of testing operations.

25. (Previously Amended) A method for testing packaged semiconductor devices, the method comprising:

performing testing of the packaged semiconductor devices;

during the testing operation, automatically determining that a cleaning is to be performed;

automatically determining the location of a working surface of a cleaning device based on a characteristic of the working surface by directing optical energy towards the working surface of the cleaning device and determining the location of the working surface of the cleaning device based on the optical energy reflected off of the working surface of the cleaning device;

performing the cleaning using the cleaning device; and

continuing testing of packaged semiconductor devices.

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26. (Previously Amended) The method of Claim 25, wherein determining the working surface of the cleaning device further comprises measuring the conductance of the working surface of the cleaning device in order to determine the position of the working surface of the cleaning device.

27. (Previously Amended) The method of Claim 25, wherein performing the cleaning further comprises moving a probe element in a horizontal motion.

28. (Previously Amended) The method of Claim 25, wherein performing the cleaning further comprises moving a probe element in an orbital motion.

29- 30. Cancelled.